

You need dummies for mechanical or electrical set-ups?  
Chips or wafers (up to 8"), we can make them.

Even for low volumes, on the shelf or specific: ask IBS!

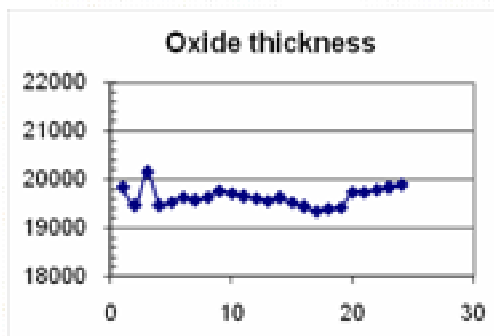
## FUNCTIONALITIES

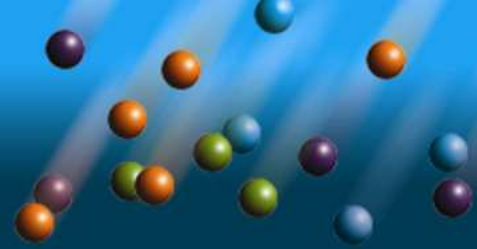
- Equipment mechanical tests
- Equipment electrical tests
- Calibration of thickness measure equipment



## REALIZATIONS

- Chip (any size) or wafers (up to 8")
- Any substrate thickness or matter
- Any deposited layer on top





## IBS PROPOSITIONS:

- Design of discrete components
- Simulations
- Masks layout
- Process Integration and manufacturing
- A scalable subcontracting: from single steps to full component

## IBS PROCESSES:

- Oxidation and thermal annealing
- Deposits: PECVD, LPCVD, Sputtering, thermal evaporation
- Photolithography: down to 1  $\mu\text{m}$  definition / double side
- Etchings: RIE, IBE, wet, TMAH (anisotropic etching for Silicon)
- Ion Implants

## IBS CHARACTERIZATION:

- Microscopy and critical dimensions (including SEM, TEM, AFM)
- SIM / TOF-SIMS / AUGER
- R-square and junction measurement
- Mechanical and optical profilometers, ellipsometer
- Manual and automatic probers

